AMENDMENTS TO THE CLAIMS:

Following is a listing of all claims in the present application, which listing supersedes all previously presented claims:

Listing of Claims:

1-5. (Cancelled)

6. (Currently Amended) An apparatus for cleaning a wafer, comprising:

a revolving chuck, for supporting and fixing the wafer;

a nozzle for spraying cleaning solution onto the wafer; [[and]]

a light source, for heating the wafer and the cleaning solution during cleaning of the wafer;

a focusing lens for condensing a beam emitted from the light source onto the wafer; and

an antipollution plate mounted between a lower part of the focusing lens and a upper part of the nozzle for preventing the focusing lens from being polluted by the cleaning solution.

7. (Canceled).

8. (Currently Amended) The apparatus according to claim [[7]] 6, wherein the antipollution plate is made of transparent ~~quartz or~~ sapphire.

9. (Previously Presented) The apparatus according to claim [[19]] 21, wherein the laser is an ultraviolet, an infrared, or a visible ray laser.

10. (Original) The apparatus according to claim 6, wherein the cleaning solution is ozone water, hydrogen water, or electrolytic-ionized water.

11. (Cancelled)

12. (Currently Amended) A method for cleaning [[the]] a wafer ~~using the apparatus according to claim 6~~, the method comprising:

rotating the wafer at a predetermined speed;

spraying cleaning solution onto the wafer through a nozzle; [[and]]

heating the wafer and the cleaning solution by a light source;

using a lens to focus light from the light source onto the wafer or the cleaning solution; and

providing an antipollution plate between the nozzle and the focusing lens to prevent the cleaning solution from reaching the focusing lens.

13. (Cancelled)

14. (Original) The method according to claim 12, wherein the cleaning solution is ozone water, hydrogen water, or electrolytic-ionized water.

15. (Previously presented) The method according to claim 12, wherein the light source emits visible radiation.

16. (Cancelled).

17. (Previously presented) The method according to claim 12, wherein the light source is a laser.

18. (Previously presented) The apparatus according to claim 6, wherein the light source emits visible radiation.

19. (Canceled).

20. (Previously presented) The apparatus according to claim 6, wherein the revolving chuck is in a chamber and the light source is mounted in the chamber.

21. (Previously presented) The apparatus according to claim 6, wherein the light source is a laser.

22. (New) The method according to claim 12, further comprising controlling a rotational speed of the wafer.

23. (New) The method according to claim 12, further comprising controlling a power of the light source.

24. (New) The method according to claim 12, further comprising controlling an amount of cleaning solution.